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FEB 11 2009

Application Serial No: 10/518,225
Responsive to the Office Action mailed on: September 11, 2008

IN THE CLAIMS**Amendments To The Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An LED chip mounting structure, comprising:
a wiring board provided with a mounting pad;
an LED chip provided with an electrode facing the mounting pad;
a bump disposed between the mounting pad and the electrode for electrically connecting the mounting pad and the electrode to each other; and
an adhesive member for fixing the LED chip to the wiring board;
wherein the adhesive member comprises an anisotropic conductive resin composite, and the bump is fusion-welded to the mounting pad and is electrically connected to the electrode by the anisotropic conductive resin composite.

Claims 2-3. (Cancelled)

4. (Currently Amended) ~~The LED chip mounting structure according to claim 1, An~~
LED chip mounting structure, comprising:
a wiring board provided with a mounting pad;
an LED chip provided with an electrode facing the mounting pad;
a bump disposed between the mounting pad and the electrode for electrically
connecting the mounting pad and the electrode to each other; and
an adhesive member for fixing the LED chip to the wiring board;
wherein the adhesive member comprises an insulating resin composite, and the
bump is fusion-welded to the mounting pad and directly abuts on the electrode without
having the insulating resin composite therebetween.

5. (Cancelled)

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6. (Original) The LED chip mounting structure according to claim 1, wherein the LED chip is further provided with an electrode that is opposite to the wiring board.
7. (Currently Amended) An LED chip mounting structure, comprising:
 - a wiring board provided with a first and a second mounting pads;
 - an LED chip provided with a first electrode facing the first mounting pad and with a second electrode facing the second mounting pad;
 - a first bump disposed between the first mounting pad and the first electrode for

and the first electrode to each other.
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